



IEEE SW Test Workshop

Semiconductor Wafer Test Workshop

June 6-9, 2010 - Rancho Bernardo Inn - San Diego, CA

CALL FOR PRESENTATIONS

The 20th Annual IEEE SW Test Workshop will be held at the Rancho Bernardo Inn in San Diego, California, from June 6-9, 2009. The Workshop will begin on Sunday afternoon with a topical tutorial, followed by a welcome reception, dinner, and a Keynote Speaker. The Technical Program will start Monday morning with 30-minute presentations in theme-oriented sessions. Poster sessions will start Monday evening and will include in-depth technical presentations on many of the topics listed below. The posters will be presented in two sessions at prearranged times but will be on display for most of the conference. SW Test EXPO 2010 will showcase many of the key suppliers to the wafer probe industry and will not conflict with the technical program. As always, there will be ample opportunities throughout the entire Workshop for networking. The workshop will conclude on Wednesday at Noon after an awards presentation and luncheon.

Topics for the podium presentations and poster sessions for 2010 will include:

- New probecard and contactor technologies
- Challenges of large area array probing
- Monitor and reduction of chip I/O pad damage
- Lead-free solder bump probing
- Massively parallel, multi-site probing
- Probe Card PCB Characterization
- Productivity improvements for high volume production
- Probe data collection, analysis, and management
- Probe Card cleaning, extending card life, improving cost of ownership
- Advances in probe process metrology tools
- Addressing unique probing requirements:

- ▶ Copper I/O pads
- ▶ RF and microwave
- ▶ Mixed signal, low noise, and parametric
- ▶ Low-k dielectric and Probe Over Active Circuitry
- ▶ Probing for Known Good Die
- ▶ High power devices
- ▶ Probe Potpourri (anything goes)

Conference registration includes all meals, refreshments, social activities, and technical program and exhibit attendance, as well as the printed proceedings distributed at the Workshop. Details regarding abstract submission for SW Test 2010 and all previous electronic versions of past Proceedings can be found at <http://www.swtest.org>. Abstracts will be reviewed for inclusion as either a podium or poster presentation unless a preference is stated by the submitter.

Important Dates:

Abstract Submission Deadline: 2/26/2010	Conference Start Date: 6/6/2010
Final Paper Submission Deadline: 5/3/2010	Conference End Date: 6/9/2010

For more information:

Dr. Jerry Broz, International Test Solutions – General Chairman jerry.broz@swtest.org
William Mann – Chairman Emeritus william.mann@ieee.org

Please visit www.swtest.org regularly for the most up-to-date information regarding the key deadlines and other important information for SW Test 2010.

The Semiconductor Wafer Test Workshop is now sponsored by the IEEE Components, Packaging, and Manufacturing Technology Society

The CPMT (<http://www.cpmt.org>) is the leading international forum for scientists and engineers engaged in the research, design and development of revolutionary advances in microsystems packaging and manufacture. SW Test remains the only IEEE-sponsored event that focuses on all aspects associated with microelectronic wafer and die level testing. Featuring both manufacturer and vendor presentations, this is not a sales show nor an academic or theoretical conference, but a probe technology forum. Attendees learn about recent developments in the industry and exchange ideas in a relaxed atmosphere with plenty of time for informal discussion and networking.



www.swtest.org



Photo courtesy of SV Probe

Photo courtesy of FormFactor

Photo courtesy of Cascade Microtech

Photo courtesy of MJC

Photo courtesy of MicroProbe

